

## CLAIMS

We claim:

1. A reinforced substrate apparatus, comprising:  
a substrate;  
a first shield coupled to the substrate; and  
a strengthening member coupled to the first shield.
2. The apparatus according to claim 1, wherein the strengthening member includes at least one elongated member.
3. The apparatus according to claim 1, further comprising at least a second shield, wherein the strengthening member is coupled to the first shield and the second shield.
4. The apparatus according to claim 3, wherein the strengthening member is soldered to at least one among the first shield and the second shield.
5. The apparatus according to claim 3, wherein the strengthening member includes a conductive material.
6. The apparatus according to claim 5, wherein the strengthening member provides a ground current pathway between the first shield and the second shield.
7. The apparatus according to claim 3, wherein the strengthening member includes at least one elongated member.
8. The apparatus according to claim 7, wherein the at least one elongated member is located between the first shield and the second shield.
9. The apparatus according to claim 7, wherein the at least one elongated member is orientated non-parallel with another elongated member.

10. The apparatus according to claim 3, wherein at least one of the first shield and the second shield includes a recessed surface and an un-recessed surface, a surface of the strengthening member is at substantially the same height as the un-recessed surface when the strengthening member is attached to at least one of the first shield and second shield within the recessed surface.
11. The apparatus according to claim 1, wherein the substrate is a substrate for a mobile electronic device.
12. The apparatus according to claim 1, wherein the strengthening member is coupled to at least the first shield without contacting the substrate.
13. A reinforced substrate apparatus, comprising:
  - a substrate;
  - a first shield coupled to the substrate;
  - at least a second shield coupled to the substrate; and
  - a strengthening member coupled to the first shield and at least the second shield.
14. The apparatus according to claim 13, wherein the strengthening member includes at least one elongated member protruding from the strengthening member.
15. The apparatus according to claim 14, wherein the elongated member is located between the first shield and the second shield without contacting the substrate.
16. The apparatus according to claim 13, wherein the reinforced substrate apparatus is a substrate for a mobile electronic device and the first shield and the second shield reduce electromagnetic interference.
17. A method of reinforcing a substrate, comprising the steps of:
  - attaching a first shield and at least a second shield to the substrate, wherein at least one among the first shield and the second shield shields circuitry on the substrate; and

coupling a strengthening member to the first shield and the second shield.

18. The method according to claim 17, further comprising the step of:  
soldering the strengthening member to at least one among the first shield and the second shield.
19. The method according to claim 17, further comprising the step of:  
providing a first shield and the second shield with a recessed portion, wherein the height of the recessed portion is substantially equal to the thickness of the strengthening member.
20. The method according to claim 17, wherein the first shield and the second shield comprise a recessed portion for receiving and coupling the strengthening member to the first shield and the second shield.